Product/Process Change Notification

N° 2021-041-A2

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting IGBTs and diodes for DSC S modules

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-23.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
  "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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Products affected	Please refer to attached affected product list 1_cip21041_A2

Detailed change information

Subject:	Several changes affecting IGBTs and diodes for DSC S modules
Reason/Motivation:	Secure and increase capacity for running and future products.

Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New wafer diameter	**Wafer diameter:** HIG-GED1, FF450*: IGBT 200 mm	**Wafer diameter:** HIG-GED1, FF450*: IGBT 200 mm and 300 mm
PROCESS - WAFER PRODUCTION: Change of specified wafer process sequence (deletion and/or additional process step)	**Frontside metal stack with TiW** HIG-GDD1, FF400*: Diode HIG-GED1, FF450*: Diode	**Frontside metal stack without TiW** HIG-GDD1, FF400*: Diode HIG-GED1, FF450*: Diode
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	**Wafer production and preassembly location** HIG-GDD1, FF400*: IGBT and diode HIG-GED1, FF450*: Diode Infineon Technologies Austria AG, Villach, Austria HIG-GED1, FF450*: IGBT Infineon Technologies Austria AG, Villach, Austria	**Wafer production and preassembly location** HIG-GDD1, FF400*: IGBT and diode HIG-GED1, FF450*: Diode Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia HIG-GED1, FF450*: IGBT Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies Dresden GmbH, Dresden, Germany

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N° 2021-041-A2

TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	**Wafer test location**	**Wafer test location**
	HIG-GDD1, FF400*: IGBT and diode HIG-GED1, FF450*: Diode Infineon Technologies Austria AG, Villach, Austria	HIG-GDD1, FF400*: IGBT and diode HIG-GED1, FF450*: Diode Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
	HIG-GED1, FF450*: IGBT Infineon Technologies Austria AG, Villach, Austria	HIG-GED1, FF450*: IGBT Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies Dresden GmbH, Dresden, Germany

Product identification

Traceability is assured via lot number.
No change in SP ordering number.

Anticipated impact of change

Based on the qualifcation performed, Infineon does not see any influence on final product integrity.

DeQuMa-ID(s): SEM-PW-02 / SEM-PW-12 / SEM-PW-13 / SEM-TF-01

Attachments

1_cip21041_A2	affected product list

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-04-01
Last order date (LOD) [2]	2022-06-08
Last delivery date (LDD) [3]	2023-06-08

[1] provided date or earlier after customer approval
[2] Last time buy volume to be placed latest until LOD
[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.

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Sales name	SP number	OPN	Package
FF400R07A01E3_S6	SP001661226	FF400R07A01E3S6XKSA2	PG-MDIP-14-1
FF450R08A03P2	SP001630036	FF450R08A03P2XKSA1	PG-MDIP-14-5